



500.36904X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): MIURA, et al.

Serial No.: 09/254,939

Filed: March 17, 1999

For: METHOD OF FABRICATING SEMICONDUCTOR
DEVICE HAVING TRENCH ELEMENT SEPARATION
STRUCTURE (AS AMENDED)

Group: 2814

Examiner: A. Mai

SUBMISSION UNDER 37 CFR 1.114

Assistant Commissioner for Patents
Washington, D.C. 20231

July 26, 2001

SIR:

In response to the Office Action mailed January 26, 2001, please amend
the above-identified application as follows:

IN THE CLAIMS

Please amend the claims presently in the application as follows:

- C1 July 21*
- 1. (Twice Amended) A method of fabricating a semiconductor device
comprising the steps of:

1 2 3 4 5 6 9 10-13 14 15-17 1

18-20 21-23 24-26 27 29 30-32 33 35 36 38

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13/Pre-
Amend
C
G. Stang
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